

Chip Termination 5 Watts, 50Ω



Features:

- 5 Watts
- Lowest Cost
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

Resistive Element	Thick film
Substrate	BeO Ceramic
Terminal Finish	Matte Tin over Nickel
Operating Temperature	-55 to +125°C (see chart)

Tolerance is ± 0.010 ", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

Electrical Specifications

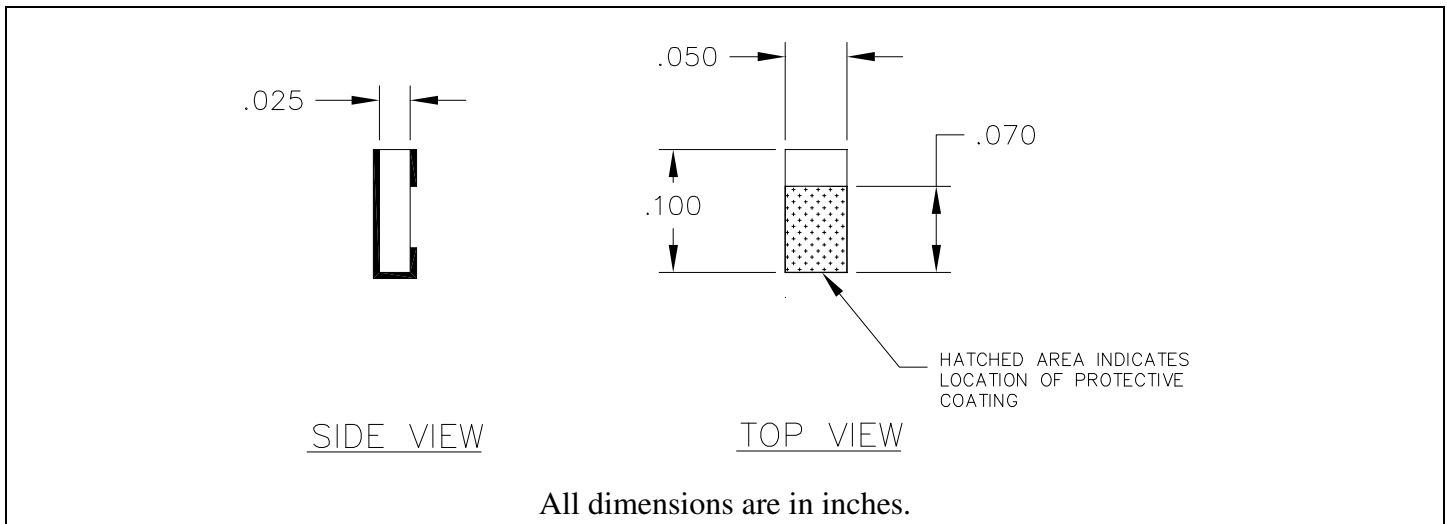
Resistance Value:	50 ohms, $\pm 2\%$
Power:	5 Watts
Frequency Range:	DC – 4.0 GHz
V.S.W.R.:	1.25:1

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance.

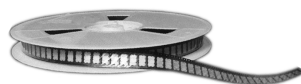
Tolerance is ± 0.010 inches.

Specifications subject to change without notice

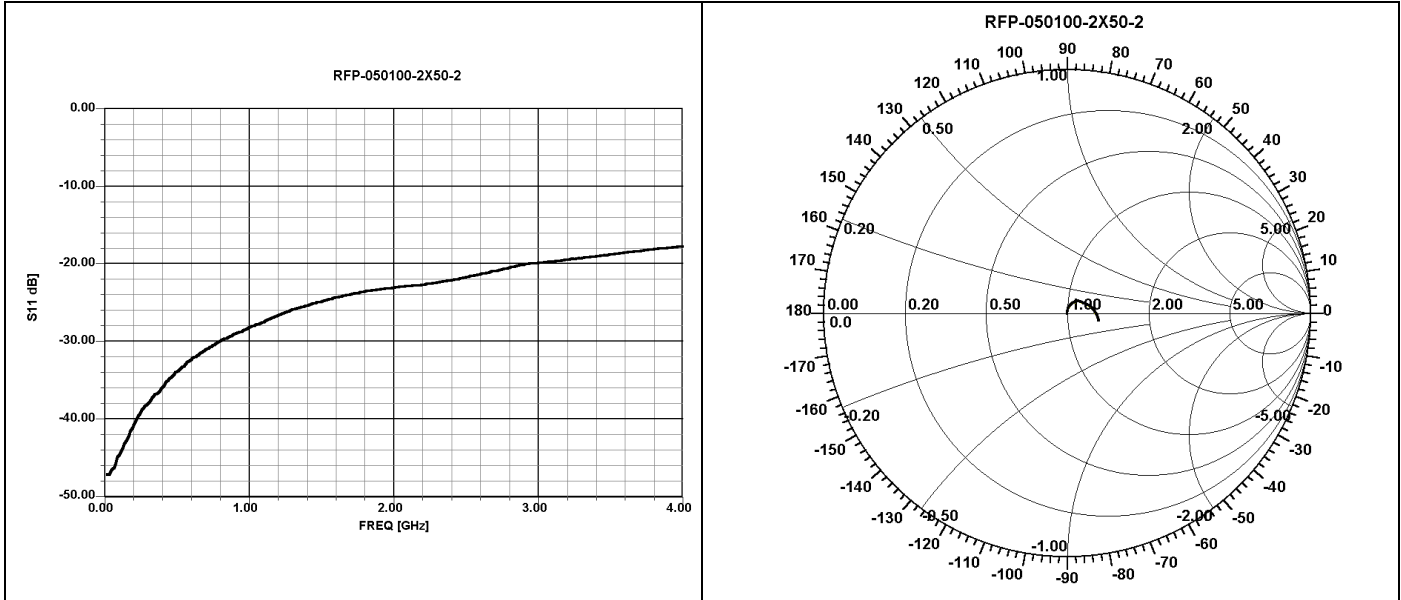
Outline Drawing



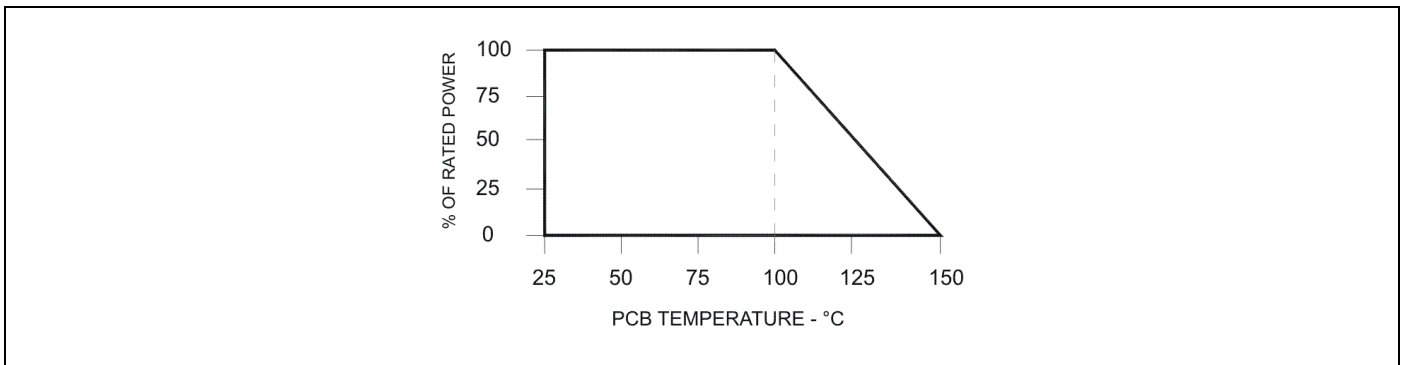
050100-2X50-2 (097) Rev B pg. 1 of 2



Typical Performance:



Power De-rating:



Mounting Footprint and Procedure:

The diagrams illustrate the correct and incorrect mounting procedures. The 'SUGGESTED STRESS-RELIEF METHODS' section shows three cross-sectional views: 'BOARD LOWER THAN LEAD', 'BOARD EVEN WITH LEAD', and 'BOARD HIGHER THAN LEAD'. The 'NOT RECOMMENDED APPLICATION' section shows a cross-section where the board is lower than the lead. A dimension of .025 MIN. (2 PLACES) is indicated for the board thickness. Below the diagrams, the text reads 'SUGGESTED MOUNTING PROCEDURES:' followed by three numbered steps.

SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. POSITION DEVICE ON MOUNTING SURFACE AND SOLDER IN PLACE USING SN96 SOLDER.
3. SOLDER LEADS IN PLACE USING AN SN96 TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON (260°C).

